

Description

The LY323DCXX is a bi-directional TVS diode array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting sensitive semiconductor components from damage. It complies with IEC 61000-4-2 (ESD), $\pm 30\text{kV}$ air and $\pm 30\text{kV}$ contact discharge. It is assembled into a lead-free SOD-323 package. It is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers and PDA's.

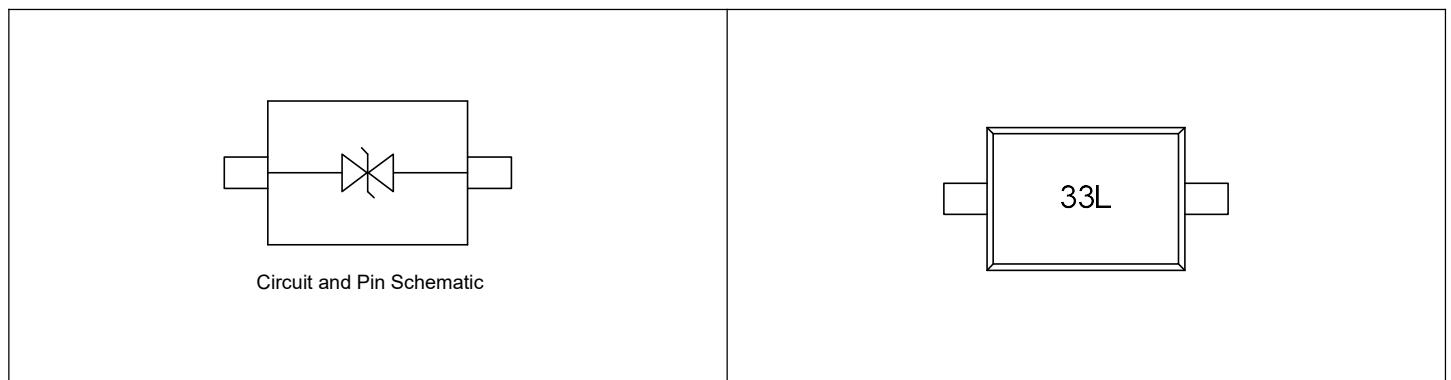
Features

- Protects one data or power line
- Ultra low leakage current
- Operating voltage: 3.3V~36V
- RoHS compliant
- IEC-61000-4-2 ESD $\pm 30\text{kV}$ Air, $\pm 30\text{kV}$ Contact
- Packaging: 7 inch reel, 3000pcs/reel

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation
- Peripherals
- Pagers Peripherals
- Desktop and Servers

Pin Configuration and Marking



Absolute Maximum Ratings (T_A=25°C)

Parameter	Symbol	Value
Peak Pulse Power (8/20μs)	P _{PP}	300W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±30kV ±30kV
Ambient Temperature Range	T _A	-55°C to +125°C
Storage Temperature Range	T _{STG}	-55°C to +150°C

Electrical Characteristics (T_A=25°C)

Part Number	Marking	Reverse Working Voltage	Reverse Breakdown Voltage @I _T =1mA	Reverse Leakage Current @V _{RWM}	Clamping Voltage @8/20μs		Peak Pulse Current	Junction Capacitance @V _R =0V, f=1MHz	
		V _{RWM} (V)	V _{BR} (V)	I _R (μA)	V _C (V)		I _{PP} (A)	C _J (pF)	
		Max.	Min.	Max.	@1A	@I _{PP} Max.	Max.	Typ.	Max.
LY323DC03	33L	3.3	3.8	1.0	6	12	25	-	100
LY323DC05	05CL	5.0	6.0	1.0	8	15	20	-	80
LY323DC12	12L	12.0	13.3	0.5	18	25	12	32	-
LY323DC24	24L	24.0	27.0	0.2	40	60	5	15	-
LY323DC36	36L	36.0	38.0	0.2	50	75	4	12	-

Typical Characteristic Curves ($T_A=25^\circ\text{C}$)

Figure 1. Peak Pulse Power Rating Curve

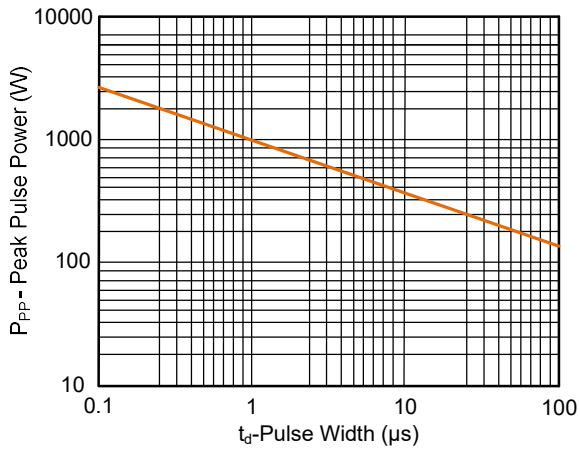


Figure 2. Pulse Derating Curve

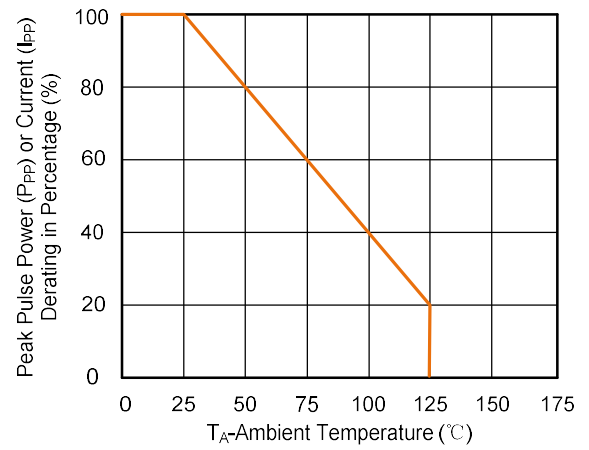


Figure 3. Pulse Waveform (8/20 μs)

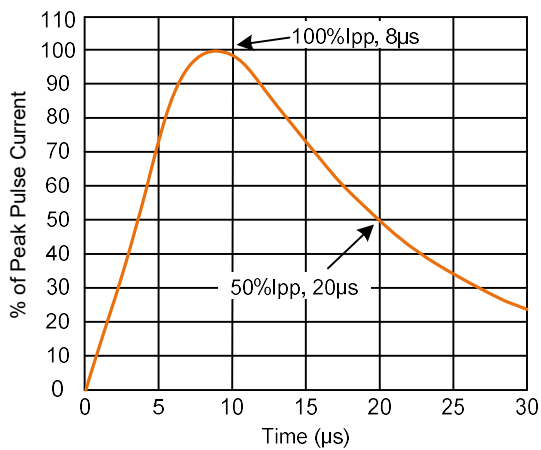
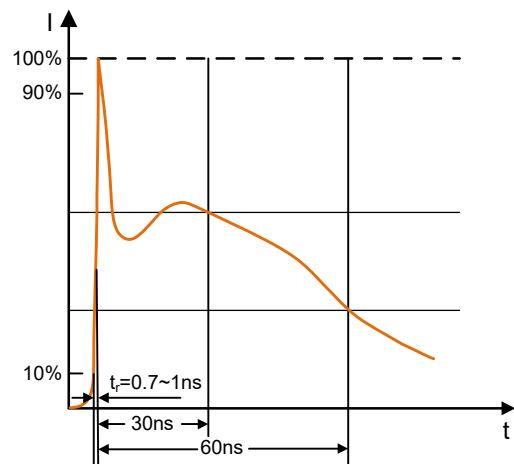
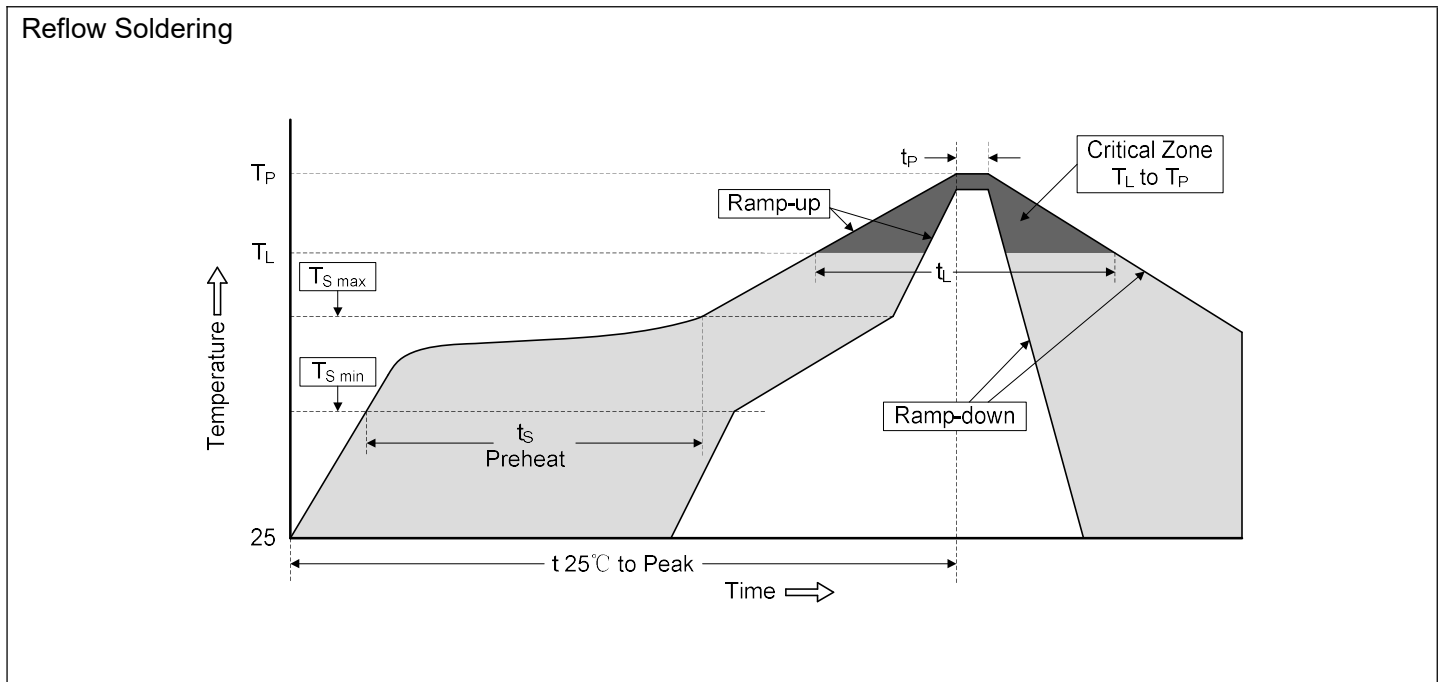


Figure 4. Pulse Waveform (IEC61000-4-2)



Soldering Parameters



Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD-323)

